

2018 IEEE 27th Conference on Electrical Performance of Electronic Packaging and Systems (EPEPS 2018)

**San Jose, California, USA
14-17 October 2018**



**IEEE Catalog Number: CFP18EPP-POD
ISBN: 978-1-5386-5167-4**

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IEEE Catalog Number:	CFP18EPP-POD
ISBN (Print-On-Demand):	978-1-5386-5167-4
ISBN (Online):	978-1-5386-5166-7
ISSN:	2165-4107

Additional Copies of This Publication Are Available From:

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